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REMARKS

Claims 1-50 are pending. Of these, claims 3, 10-16, 23, and 38-50 stand withdrawn from consideration. In the above amendment, claim 37 has been amended to correct its dependency, and claim 42 has been amended to make a minor correction.

Allowable Subject Matter

The indication that claims 2 and 17-22 constitute allowable subject matter is noted with appreciation.

Prior Art Rejections

Claims 1, 4-9, and 24-37 stand rejected under 35 USC 103(a) as obvious over Oberle, U.S. Patent No. 6,476,775 ("Oberle"). Withdrawal of the rejections is respectfully requested for at least the following reasons.

Oberle describes a method of making a radio frequency antenna. According to one embodiment of Oberle, a coil pattern conductive seed layer 51 is first formed on top of a flexible substrate 53. FIG. 4A; col. 3, lines 44-56. An electrical short layer 54 is used to couple together various turns of the coil pattern in the conductive seed layer 51, to facilitate electroplating. FIG. 4B; col. 3, line 56 – col. 4, line 1. After an insulating layer 56 is placed atop the electrical short layer 54, electroplating is used to thicken the antenna by depositing a patterned conductive layer 58 atop the conductive seed layer 51. FIG. 4C; col. 4, lines 1-8. The electrical short layer 54 and the insulating layer 56 are then stripped away, leaving the thickened coil pattern of conductive material. FIG. 4D; col. 4, lines 8-11. No attachment of a strap or chip is mentioned with regard to this embodiment.

Another embodiment of Oberle involves holes 102 and 104 in a flexible substrate material 100. A conductive foil shunt 106 is placed on a bottom side 100b of the substrate 100, opposite a top side 100a upon which a conductive pattern 110 is placed, and then thickened by electroplating. FIGS. 7A-8D, col. 4, line 48 – col. 5, line 11.

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Oberle mentions that an integrated circuit is connected to conductive pads 112 and 114 of the conductive pattern 110, col. 4, lines 56-59, but does not mention how the integrated circuit is connected. Oberle does disclose use of straps, or use of crimping.

Claim 1 recites a method of making an RFID device that includes, *inter alia*, attaching a strap to the substrate, wherein the attaching includes crimping to form crimped electrical connections between a seed layer and conductive leads of the strap, and wherein the crimped electrical connections pass through the substrate. Oberle does not teach or suggest making the recited crimped electrical connections between a strap and a substrate. Oberle's conductive material 58 is described in the Action as a "strap," page 3, but the conductive material is not a strap at all, but merely patterned, electroplated conductive material. The term "strap" is defined in the specification as referring "broadly to devices that include a microchip or other electronic circuitry, coupled to conductive leads," paragraph [0047]. Oberle's electroplated conductive material 58 is not a strap and does not suggest a strap.

Moreover, Oberle does not teach or suggest a strap, much less crimped electrical connections for attaching a strap to a substrate. Although Oberle makes a brief mention of an integrated circuit, Oberle says nary a word regarding how the mentioned integrated circuit is coupled to the conductive pads 112 and 114. Oberle does not mention or suggest at all a strap, "a microchip or other electronic circuitry, coupled to conductive leads," as the term is defined in the specification of the present application. Nor does Oberle teach or suggest crimped electrical connections between a strap and a substrate that pass through the substrate. Since Oberle does not teach or suggest all of the recited features of claim 1, claims 1, 4-9, and 24-37 are patentable over Oberle.

Oberle also fails to teach or suggest the features of dependent claims 4-9. Dependent claims 4-9 all involve plating after attaching the strap to the substrate. Oberle appears to contemplate only formation of the conductive pattern antenna prior to connection of an integrated circuit. Nothing in Oberle is believed to teach or suggest

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plating after attachment. Therefore for additional reasons claims 4-9 are patentable over Oberle.

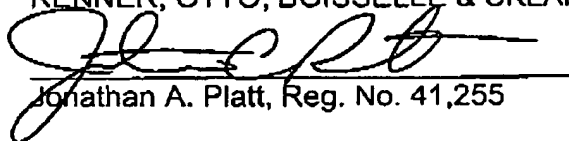
Conclusion

In view of the above, withdrawal of the rejections is respectfully requested, which would put the application into condition for allowance. Early action to that end is requested.

Should the Examiner believe that a telephone interview would be helpful to expedite favorable prosecution, the Examiner is invited to contact Applicant's undersigned attorney at the telephone number listed below.

It is believed no fee is required with the filing of this paper. In the event any fees are due in connection with the filing of this paper, the Commissioner is authorized to charge those fees to Deposit Account No. 18-0988 (Charge No. AVERP3408US).

Respectfully submitted,  
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